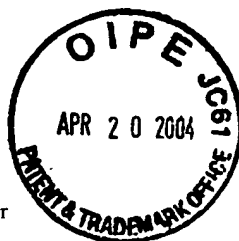


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Customer Number

Patent
Case No.: 58196US007**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

First Named Inventor: AUSEN, RONALD W.
Application No.: 10/786486 Group Art Unit: Unknown
Filed: February 25, 2004 Examiner: Unknown
Title: HEAT TREATED HIGH DENSITY STRUCTURES

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:	
Date 4/13/04	Signed by: Cheryl L. Schmitz <i>Cheryl L. Schmitz</i>

Dear Sir:

Pursuant to 37 CFR §§1.56, 1.97, and 1.98, enclosed is a completed Form PTO-1449, citing references submitted for consideration by the Examiner. Copies of any cited foreign patents and non-patent literature documents are enclosed. Pursuant to the waiver in the Pre-OG Notice, dated July 11, 2003, copies of US patents and published US patent applications are no longer required and are not enclosed. It is respectfully requested that the Examiner initial and return the enclosed Form PTO-1449 to indicate that each reference has been considered.

Under 37 CFR §1.97(e)(1), I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three (3) months prior to the filing of this Information Disclosure Statement.

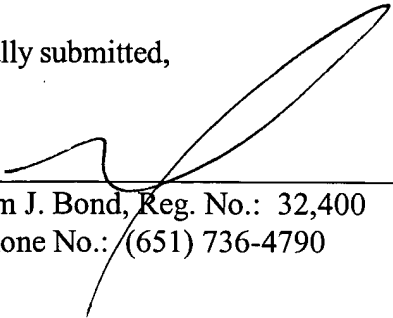
Under 37 CFR §1.704(d), I hereby state that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart application and that this communication was not received by any individual designated in 37 CFR § 1.56(c) more than thirty (30) days prior to the filing of this Information Disclosure Statement.

A copy of the Search Report from a foreign counterpart application is enclosed.

It is believed that no fee is due; however, in the event a fee is required, please charge the fee to Deposit Account No. 13-3723.

Respectfully submitted,

April 13, 2004
Date

By: 
William J. Bond, Reg. No.: 32,400
Telephone No.: (651) 736-4790

Office of Intellectual Property Counsel
3M Innovative Properties Company
Facsimile No.: 651-736-3833

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Filing Date

February 25, 2004

First Named Inventor

Ausen, Ronald W.

Art Unit

3677

Examiner Name

Unknown

Attorney Case Number

58196US007

(Use as many sheets as necessary)

APR 20 2004

Page 1 of 1

U.S. Patent Documents

Exam. Init.*	Cite No.	Document Number	Publication Date or Issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Doc. Number-(Kind Code if Known)			
	A1	US- 6,066,281	05/23/2000	Provost	
	A2	US- 6,303,062	10/16/2001	Aamodt et al.	
	A3	US-			
	A4	US-			
	A5	US-			
	A6	US-			
	A7	US-			
	A8	US-			
	A9	US-			
	A10	US-			
	A11	US-			

Foreign Patent Documents

Exam. Init.*	Cite No.	Foreign Patent Document		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	Translation (Check if yes)
		Ctry. Code	Number-KindCode (If known)				
	B1	WO	03/059108	07/24/2003			X
	B2						
	B3						
	B4						
	B5						
	B6						
	B7						

OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS

Exam. Init.*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published
	C1	
	C2	
	C3	

*Examiner:

Date Considered:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.